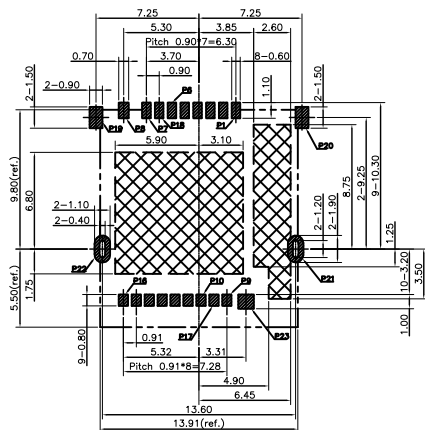
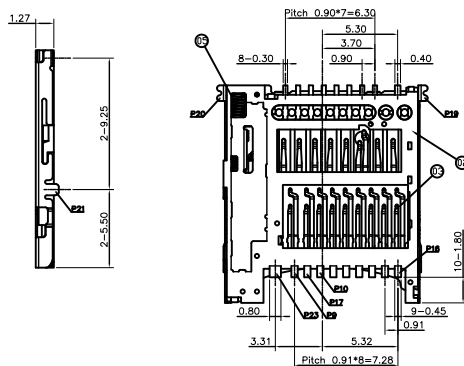
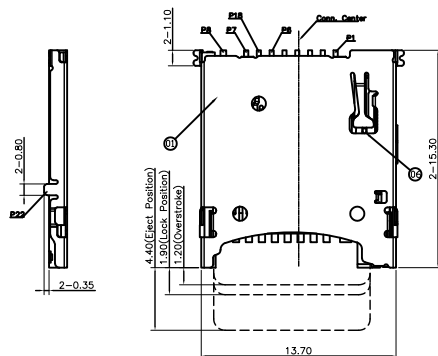
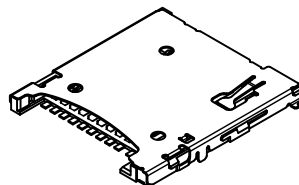
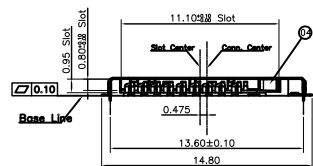
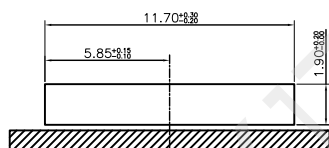
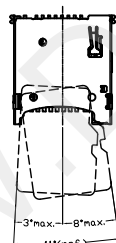


Recommended PCB Layout
Top View (Tolerance 0.05)

- Pad Area
 Other Component Keepout Area
 No Pattern Area



Recommended ID Dimension



Card Insertion Guide Angle

	Card Detect Switch
Card Uninsertion	Open
Card Half Insertion	Open
Card Insertion	Close
Open	Close
P6 P18	P6 P18

Pin No.	Pin Assignment (microSD Card)	Pin Assignment (UHS-II microSD Card)	Pin Assignment (microSD Express Card)
P1	Micro SD DAT2	Micro SD DAT2	Micro SD DAT2
P2	Micro SD CD/DAT3	Micro SD CD/DAT3	Micro SD CD/DAT3
P3	Micro SD CMD	Micro SD CMD	Micro SD CMD
P4	Micro SD VDD1	Micro SD VDD1	Micro SD VDD1
P5	Micro SD CLK	Micro SD CLK	Micro SD CLK
P6	Micro SD VSS	Micro SD VSS	Micro SD VSS
P7	Micro SD DAT0/RCLK+	Micro SD DAT0/RCLK+	Micro SD DAT0/RCLK+
P8	Micro SD DAT1/RCLK-	Micro SD DAT1/RCLK-	Micro SD DAT1/RCLK-
P9	Micro SD VDD2	Micro SD VDD2	Micro SD VDD2
P10	Micro SD VSS	Micro SD VSS	Micro SD VSS
P11	Micro SD D0+	PCIe Tx +	PCIe Tx +
P12	Micro SD D0-	PCIe Tx -	PCIe Tx -
P13	Micro SD VSS	Micro SD VSS	Micro SD VSS
P14	Micro SD D1-	PCIe Rx -	PCIe Rx -
P15	Micro SD D1+	PCIe Rx +	PCIe Rx +
P16	Micro SD VSS	VSS	VSS
P17	Micro SD SWIO	VDD3	VDD3
P18	Micro SD CD	Micro SD CD	Micro SD CD
P19	Shielding GND	Shielding GND	Shielding GND
P20	Shielding GND	Shielding GND	Shielding GND
P21	Shielding GND	Shielding GND	Shielding GND
P22	Shielding GND	Shielding GND	Shielding GND
P23	Shielding GND	GND	GND

6	Link	IPad	SUS304-H T=0.25±0.05mm	Not plating
5	Spring	IPad	SVP-3	Underplating Ni
4	Slide	IPad	PA9T UL94V-0, Black	
3	Terminal	IPad	Copper Alloy (CSE18R-SH17-0.08±0.05mm)	Contact area: Gold 50" min. Solderable: Matted TIN 80" min. Over Ni 50" min.
2	Housing	IPad	High Temperature Thermoplastic UL 94V-0	Black
1	Shell	IPad	SUS304-H T=0.25±0.05mm	Underplating Ni overall 50" min
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

Note:

1. Material:

1-1. Plastic: LCP, Black, UL94V-0

1-2. Contact: Copper Alloy

1-3. Shell: Stainless Steel

2. Plating:

2-1. Contact:

Contact Area: Au 50" min. Plating Over Ni 50u" min.

Solderable: Matted TIN 80u" min. Over Ni 50u" min.

2-2. Shell:

Solderability Ni 50u" min. Over All

3. Contact And Tail Coplanarity To Be 0.10mm max.



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.X' ±2" X.X" ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: TF 7.1 PUSH 1.27H
UNIT: mm [inch] SCALE:1:1 SIZE: A4	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC189-TF23-127
	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.
			DRAW NO: HYC-2602021011
			SHEET NO. 1 OF 1